

April 2000

FQB2N90 / FQI2N90

900V N-Channel MOSFET

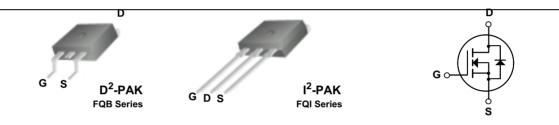
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply.

Features

- 2.2A, 900V, R_{DS(on)} = 7.2 Ω @ V_{GS} = 10 V Low gate charge (typical 12 nC)
- Low Crss (typical 5.5 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB2N90 / FQI2N90	Units
V _{DSS}	Drain-Source Voltage		900	V
I _D	Drain Current - Continuous (T _C = 25°C)		2.2	Α
	- Continuous (T _C = 100°C)	1.39	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	8.8	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	170	mJ
I _{AR}	Avalanche Current	(Note 1)	2.2	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	8.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.0	V
P _D	Power Dissipation (T _A = 25°C) *		3.13	W
	Power Dissipation (T _C = 25°C)		85	W
	- Derate above 25°C		0.68	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.47	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		900			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced	to 25°C		1.0		V/°C
I _{DSS}	7 0 1 1/1 5 1 0 1	V _{DS} = 900 V, V _{GS} = 0 V				10	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 720 V, T _C = 125°C				100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 1.1 A			5.6	7.2	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 1.1 A	(Note 4)		2.0		S
C _{iss}	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			390 45	500 60	pF pF
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$			390	500	pF
C _{rss}	Reverse Transfer Capacitance	- 1 - 1.0 WH12			5.5	7.0	pF
Switchi	ing Characteristics					I	
t _{d(on)}	Turn-On Delay Time	V _{DD} = 450 V, I _D = 2.2 A,			15	40	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$			35	80	ns
t _{d(off)}	Turn-Off Delay Time		(1)-1- 4 5)		20	50	ns
t _f	Turn-Off Fall Time		(Note 4, 5)		30	70	ns
Qg	Total Gate Charge	$V_{DS} = 720 \text{ V}, I_{D} = 2.2 \text{ A},$			12	15	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V			2.8		nC
Q_{gd}	Gate-Drain Charge	I	(Note 4, 5)		6.1		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings	;				
I _S	Maximum Continuous Drain-Source Diode Forward Current				2.2	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode F	aximum Pulsed Drain-Source Diode Forward Current				8.8	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V, } I_{S} = 2.2 \text{ A}$				1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 2.2 \text{ A},$			400		ns
Q _{rr}	Reverse Recovery Charge	dl _F / dt = 100 A/μs	(Note 4)		1.6		μC

- $\label{eq:Notes:1} \begin{tabular}{ll} \textbf{Notes:} \\ 1. & \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature} \\ 2. & \textbf{L} = 65mH, \textbf{I}_{AS} = 2.2A, \textbf{V}_{DD} = 50V, \textbf{R}_{G} = 25~\Omega, \textbf{Starting T}_{J} = 25^{\circ}\text{C} \\ 3. & \textbf{I}_{SD} \leq 2.2A, \textbf{di/dt} \leq 200\text{A/us, V}_{DD} \leq \textbf{BV}_{DSS}, \textbf{Starting T}_{J} = 25^{\circ}\text{C} \\ 4. & \textbf{Pulse Test: Pulse width} \leq 300\mu\text{s, Duty cycle} \leq 2\% \\ 5. & \textbf{Essentially independent of operating temperature} \\ \end{tabular}$

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Typical Characteristics

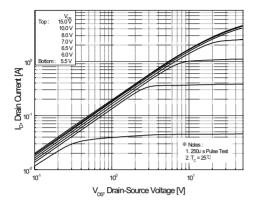


Figure 1. On-Region Characteristics

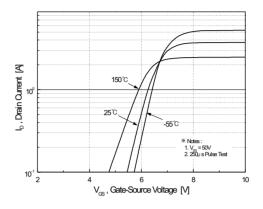


Figure 2. Transfer Characteristics

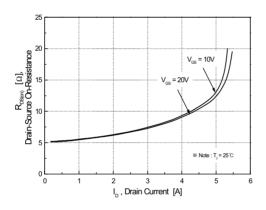


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

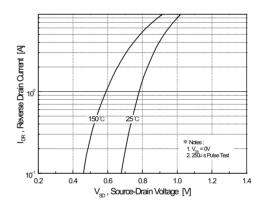


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

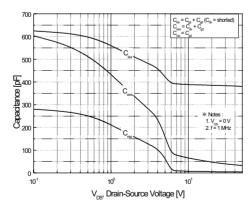


Figure 5. Capacitance Characteristics

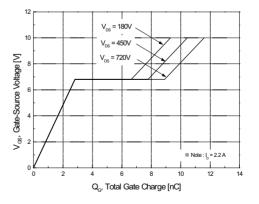
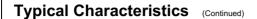
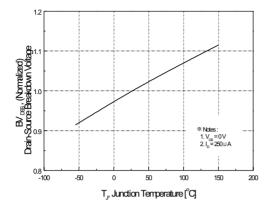


Figure 6. Gate Charge Characteristics





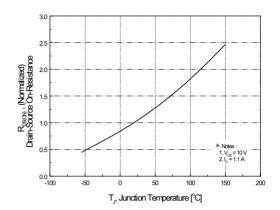
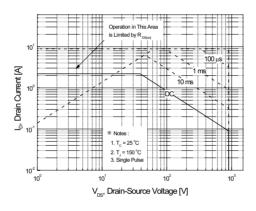


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



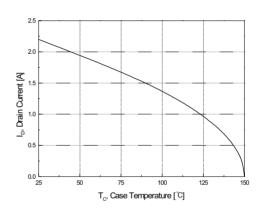


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

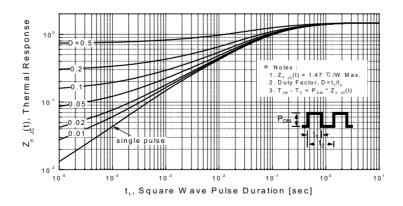
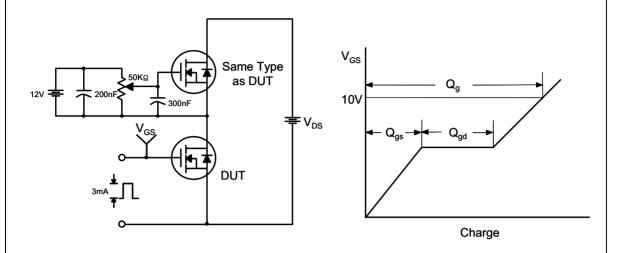


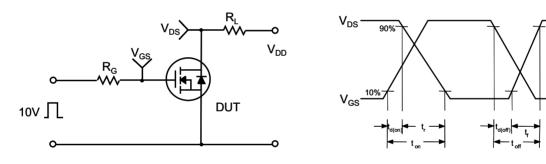
Figure 11. Transient Thermal Response Curve

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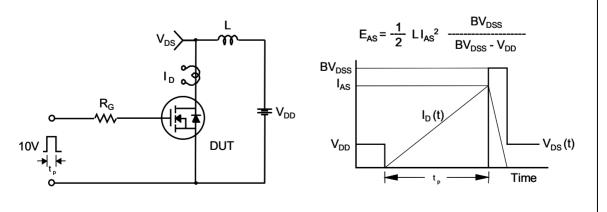
Gate Charge Test Circuit & Waveform



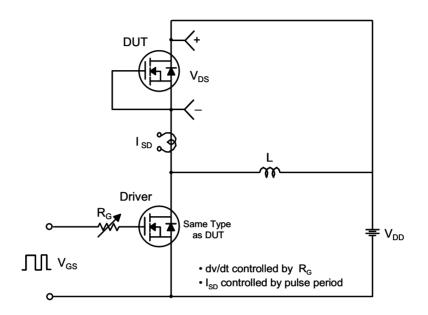
Resistive Switching Test Circuit & Waveforms

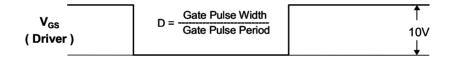


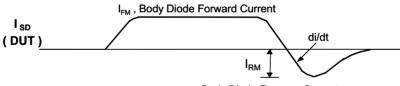
Unclamped Inductive Switching Test Circuit & Waveforms



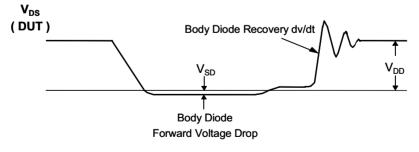
Peak Diode Recovery dv/dt Test Circuit & Waveforms



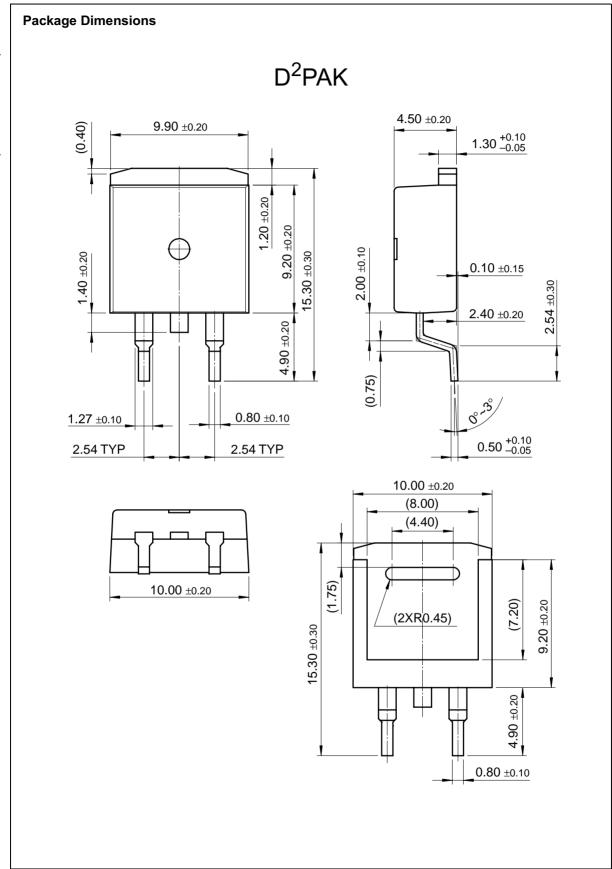




Body Diode Reverse Current



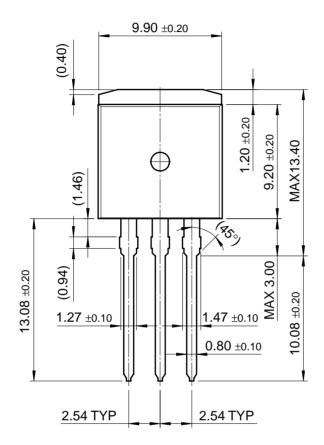
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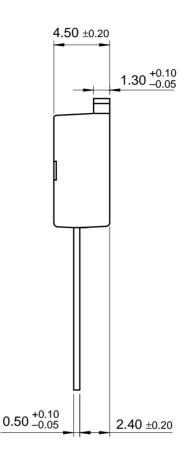


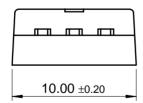
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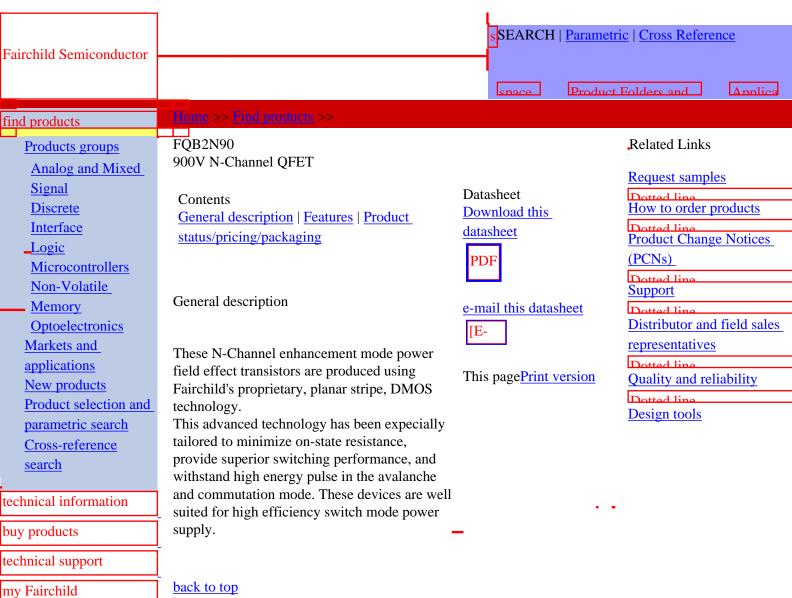
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Definition of Terms

Datasheet Identification	Product Status	Definition
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Features

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- 2.2A, 900V, $R_{DS(on)} = 7.2\Omega$ @ $V_{GS} = 10$
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- Low Crss (typical 5.5 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

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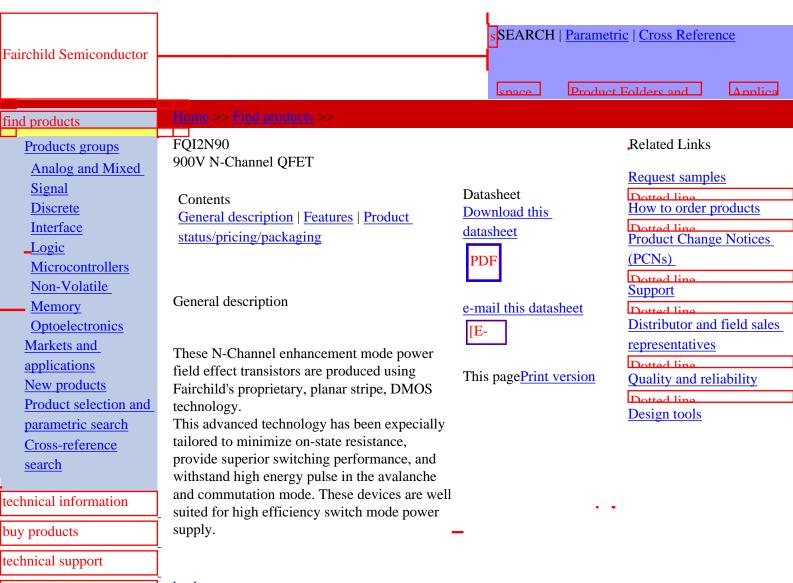
Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQB2N90TM	Full Production	\$0.75	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQI2N90TU	Full Production	\$0.75	TO-262(I2PAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

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